

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Yong-il Park</td> <td>02/21/2011</td> </tr> <tr> <td>Eun Hyung Kim</td> <td>02/21/2011</td> </tr> <tr> <td>Sung Bum Park</td> <td>02/21/2011</td> </tr> </tbody> </table>		Name	Execution Date	Yong-il Park	02/21/2011	Eun Hyung Kim	02/21/2011	Sung Bum Park	02/21/2011
Name	Execution Date								
Yong-il Park	02/21/2011								
Eun Hyung Kim	02/21/2011								
Sung Bum Park	02/21/2011								
RECEIVING PARTY DATA									
Name:	KUMOH NATIONAL INSTITUTE OF TECHNOLOGY INDUSTRY-ACADEMIC COOPERATION FOUNDATION								
Street Address:	1, Yangho-dong								
Internal Address:	Gumi-si								
City:	Gyeongbuk								
State/Country:	REPUBLIC OF KOREA								
Postal Code:	730-390								
PROPERTY NUMBERS Total: 1									
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13016245</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13016245				
Property Type	Number								
Application Number:	13016245								
CORRESPONDENCE DATA									
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NAME OF SUBMITTER:	Sun Y. Pae								

CH \$40.00 13016245

Total Attachments: 2
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Attorney Docket No.
OPT1136343US (38309-86493)

U.S. Serial No. 13/016,245

Filed: January 28, 2011

ASSIGNMENT

WHEREAS, we, Yong-il Park, residing at 202-1405, Buyeong 2-cha Apt., Okgye-dong, Gumi-si, Gyeongbuk, 730-772, Republic of Korea; Eun Hyung Kim, residing at 989-9, Daemyeong 6-dong, Nam-gu, Daegu, 705-806, Republic of Korea; and Sung Bum Park, residing at 468-5, Sajeong-dong, Gyeongju-si, Gyeongbuk, 780-939, Republic of Korea, have invented new and useful improvements in **HIGH MOLECULAR NANOCOMPOSITE MEMBRANE FOR DIRECT METHANOL FUEL CELL, AND MEMBRANE-ELECTRODE ASSEMBLY AND METHANOL FUEL CELL INCLUDING THE SAME**, and have filed a United States patent application therefor, the application serial number and filing date for which is noted above, and

WHEREAS, **KUMOH NATIONAL INSTITUTE OF TECHNOLOGY INDUSTRY-ACADEMIC COOPERATION FOUNDATION**, an entity organized and existing under the laws of the Republic of Korea, having a place of business at 1, Yangho-dong, Gumi-si, Gyeongbuk, 730-390, Republic of Korea (hereinafter **Assignee**), is desirous of acquiring the entire right, title, and interest in and to said invention, said application, and in to and under all Letters Patent of the United States and foreign countries that may be granted therefor;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that for and in consideration of the sum of One Dollar (\$1.00) and other good and valuable consideration to me in hand and paid by said **Assignee** the receipt of which is hereby acknowledged, we, said Yong-il Park, Eun Hyung Kim and Sung Bum Park have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over to and unto said **Assignee**, its successors and assigns, for, within and throughout the United States and the territories thereof, and all foreign countries, the entire right, title and interest in and to said invention, and in, to and under said application, and all Letters Patent of the United States and foreign countries that may be granted for said invention and improvements, including regular utility patent applications, divisions, reissues, subdivisions, continuations and prolongations of such applications and

Letters Patent, to have and to hold for the sole and exclusive use and benefit of said Assignee its successors and assigns, to the full end of the term or terms for which any and all of said Letters Patent for said invention may issue, and further, including the right to Assignee to file in its name applications for Letters Patent to said improvements in any country or countries foreign to the United States including the full right to claim for any such applications the priority benefits of the International Convention for the Protection of Industrial Property and other priority conferring treaties, and all Letters Patent which may be granted for said improvements in any country or countries foreign to the United States and all extensions, renewals and reissues thereof.

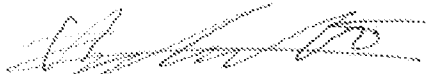
We do hereby covenant and agree, for ourselves, heirs and legal representatives, that we will assist said Assignee in the prosecution of the application herein identified; in the making and prosecution of any other applications for Letters Patent that said Assignee may elect to make covering the invention herein identified, as hereinbefore set forth; in vesting in said Assignee, like exclusive title in and to all such other applications and Letters Patent; and in the prosecution of any interference which may arise involving said invention, or any application or Letters Patent herein contemplated; and that we will execute and deliver to said Assignee, any and all additional papers that may be requested by said Assignee, to fully carry out the terms of this assignment.

And we do hereby authorize and request the Commissioner of Patents to issue all Letters Patent of the United States that may be granted pursuant to application aforesaid, or for said invention, to said Assignee, its successors and assigns in accordance with this assignment.

And we hereby covenant that we have full right to convey the entire interest herein assigned, and that we have not executed and will not execute any agreement in conflict herewith.

2011. 2. 21

Date



Yong-il Park

2011. 2. 21

Date

Kim Eun Hyung

Eun Hyung Kim

2011. 7. 21

Date

park Sung Bum

Sung Bum Park